

# **Application and Extraction of IC Package Electrical Models for Support of Power and Signal Integrity Analysis**

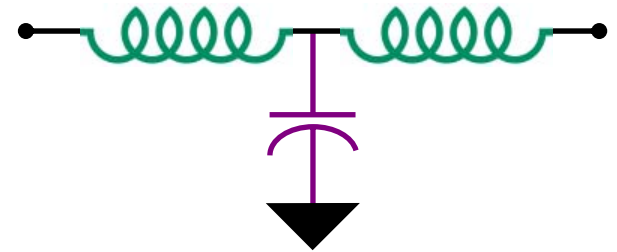
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Sigrity Inc, Santa Clara, CA

# Focus:

- Understand how extraction conditions, model type and electrical analysis application dictate requirements for IC package models.
- Sigrity's package extraction tool XtractIM<sup>®</sup> is applied.
- We examine
  - extraction frequency for 1-segment RLCK model
  - bandwidth of data upon which model is based  
(*DC, low frequency, broadband circuit parameters*)
  - type and bandwidth of model  
(*lumped to fully distributed*)
  - edge rate of the switching signals  
(*effective bandwidth of signals*)
  - effects of above choices on PI-SI simulation of noise in high-speed package systems

# Single-segment RLCK Models



## Bandwidth

- net length < 10% wavelength
- plane size < 15% to 20% of first resonance (*without decaps*)

Estimated reliably by considering length of longest signal net.

## Extraction

- DC data: (a) split DC inductance to form symmetric T-circuit
- AC data: (b) closed form equation fit to single frequency point data  
(c) optimize to broadband data

## AC single-frequency extraction

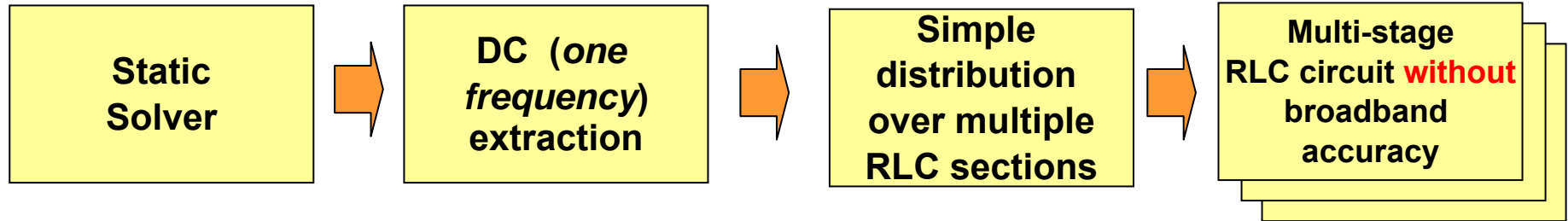
- any frequency ( $F_0$ ) **in this bandwidth** can be applied (*including DC*)
- R increases with  $F_0$
- L decreases initially with  $F_0$ , then increases with skin loss
- C insensitive to  $F_0$

## AC multi-frequency extraction

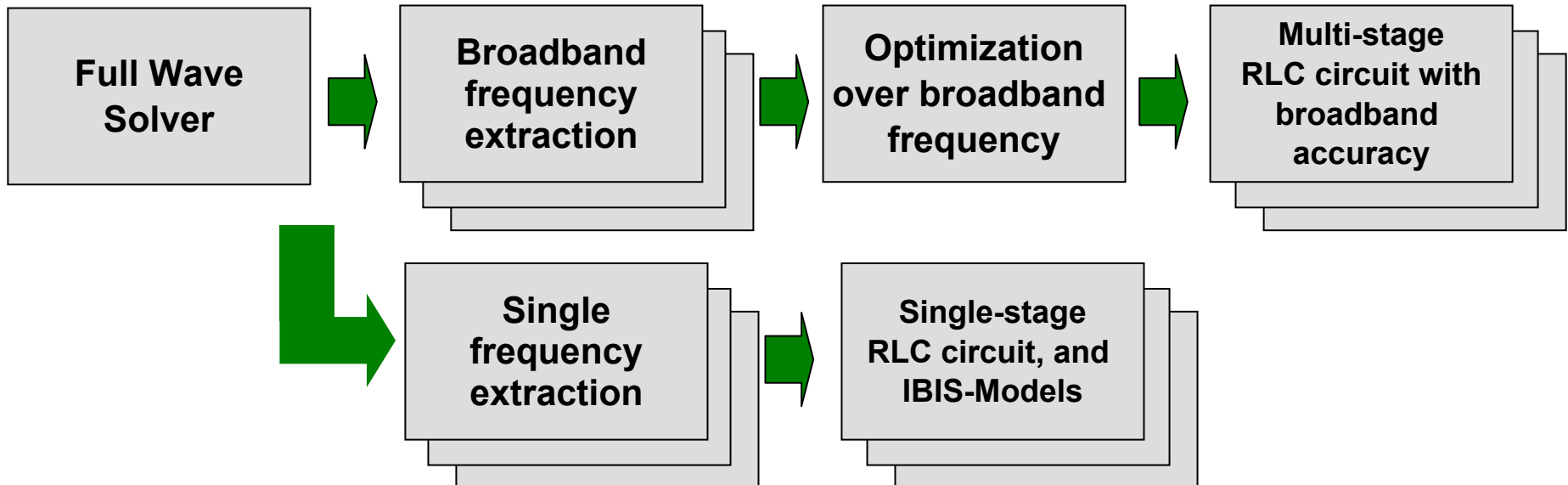
- maximum frequency should be in this bandwidth

# Electrical Package Model Extraction

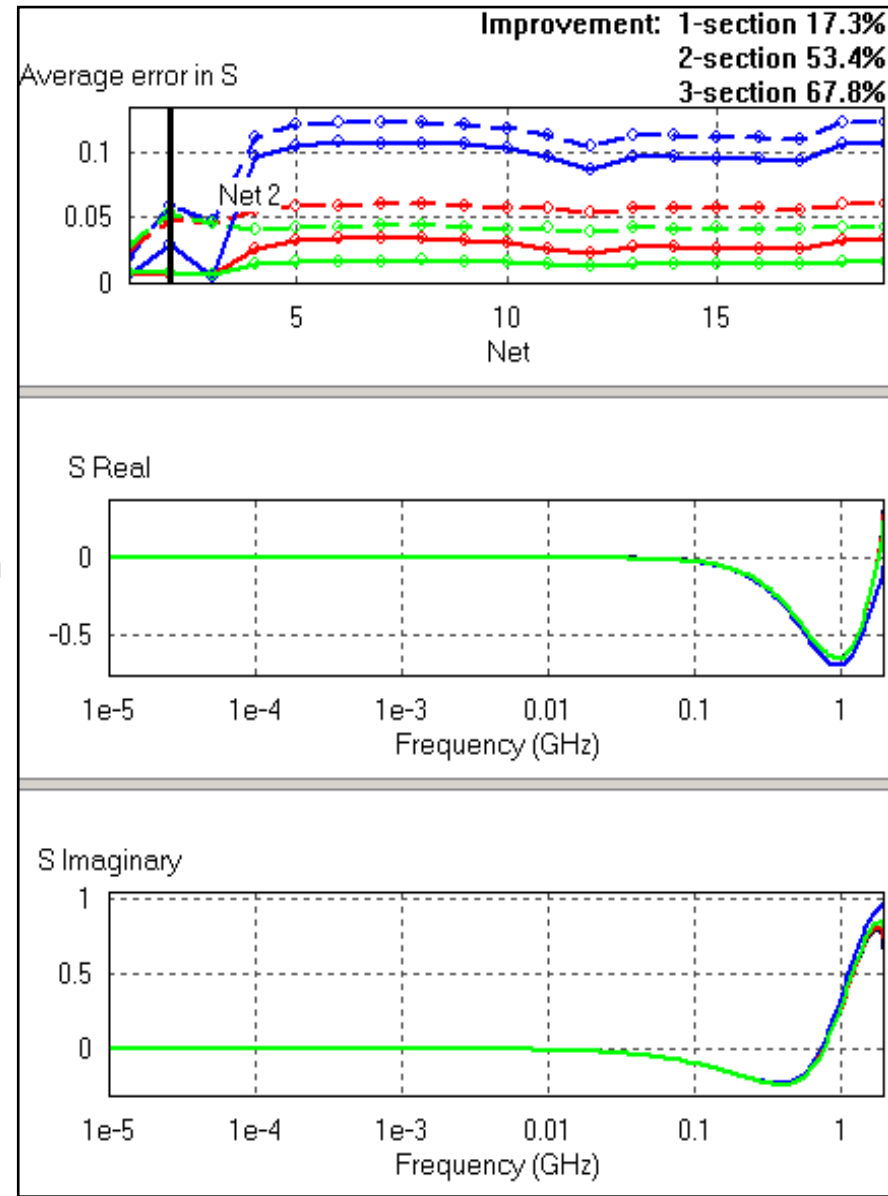
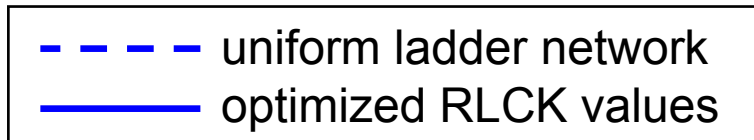
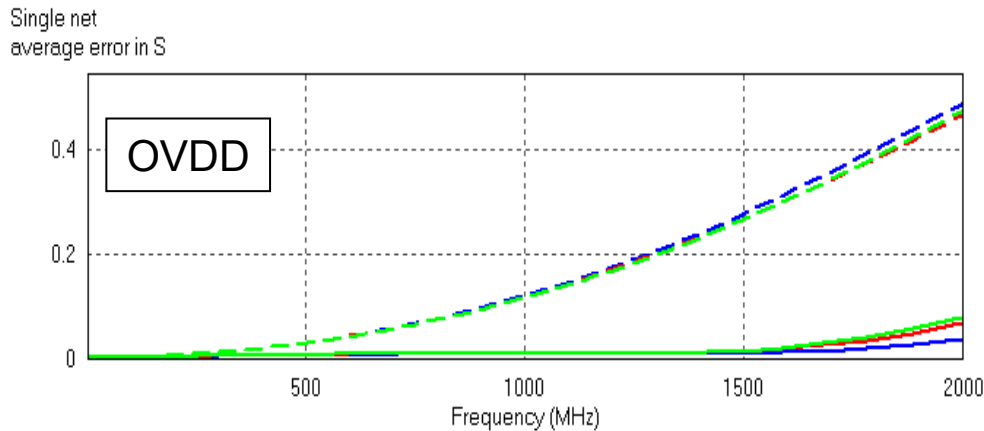
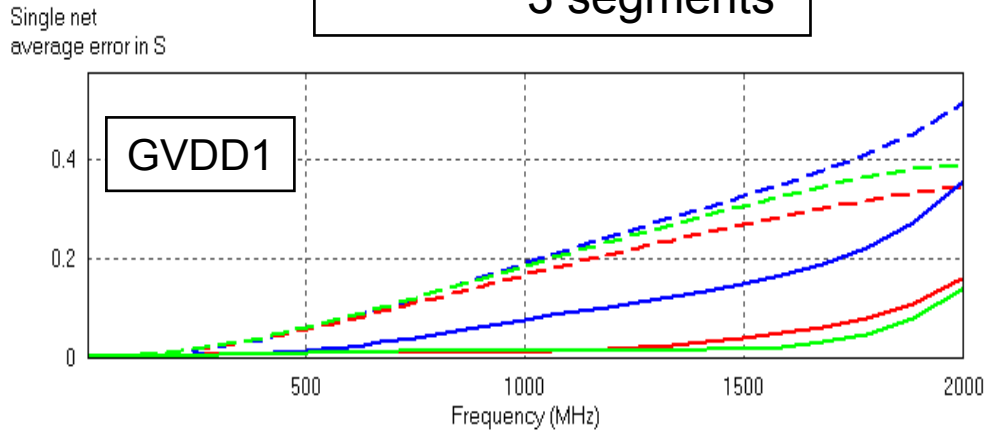
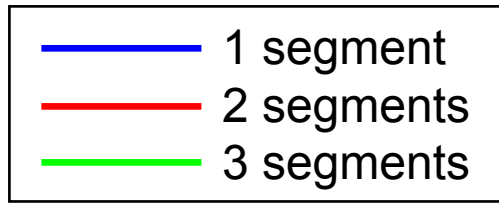
## Traditional Approach



## XtractIM Approach

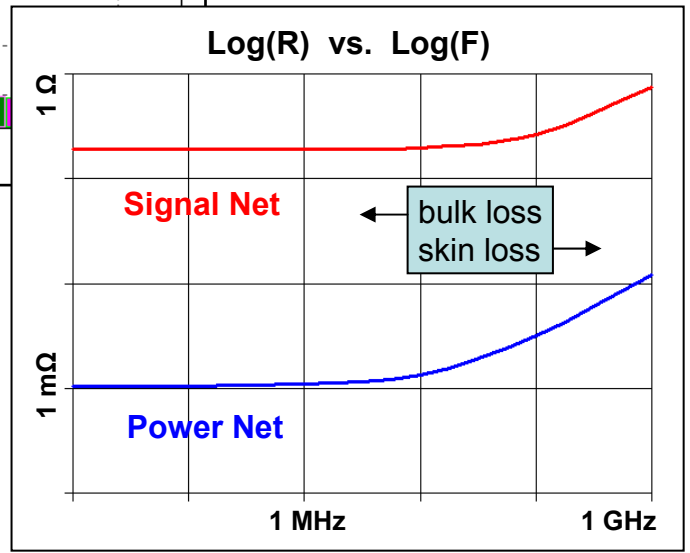
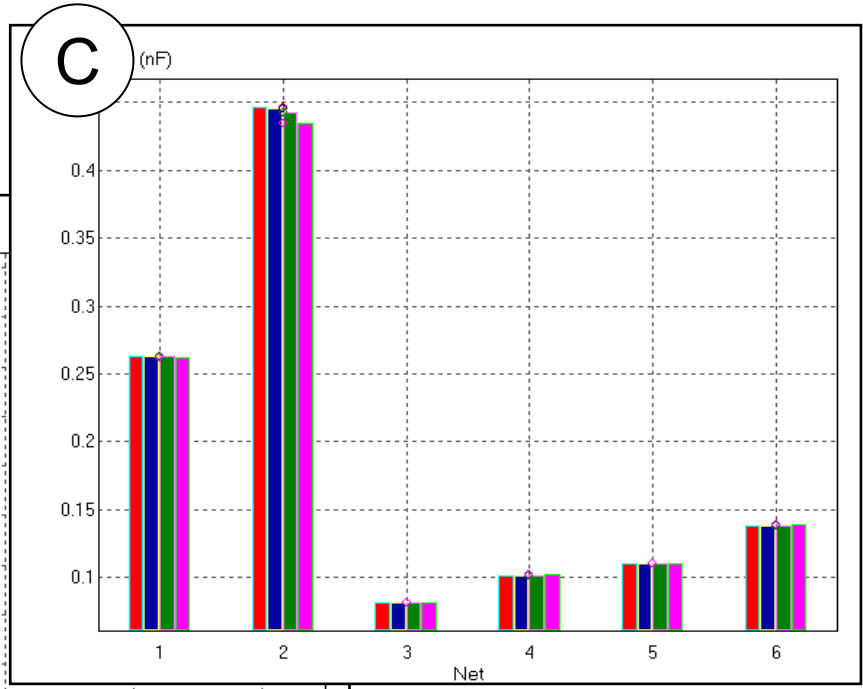
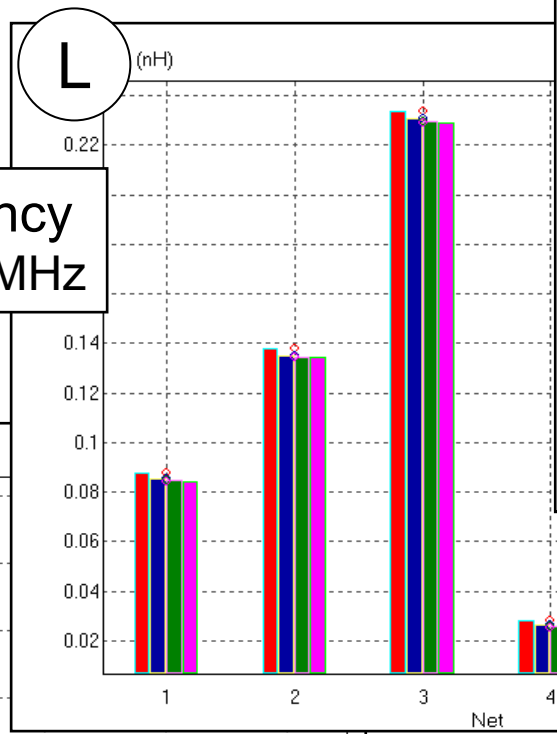
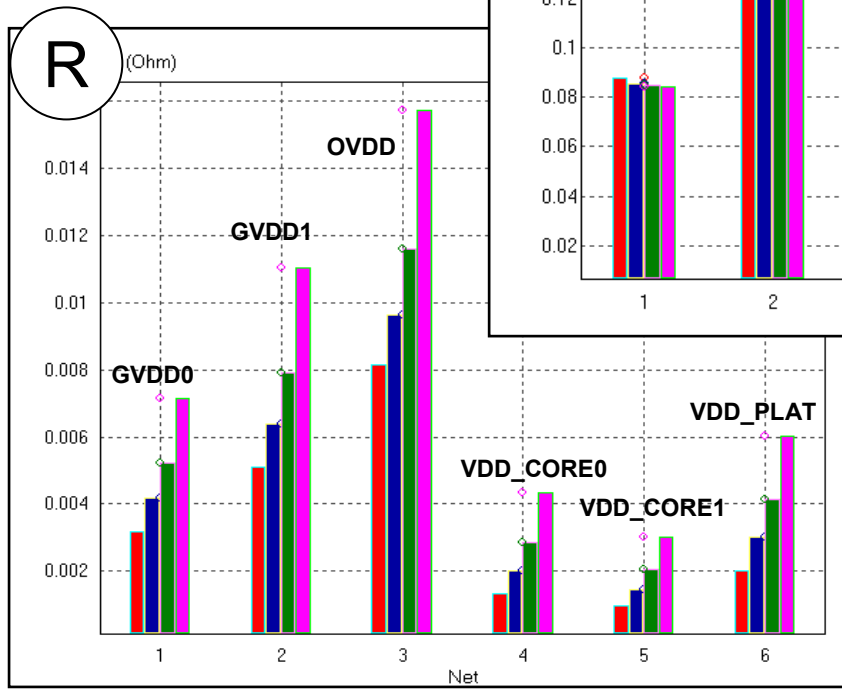


# Optimized Broadband RLCK Model: DC to 2 GHz



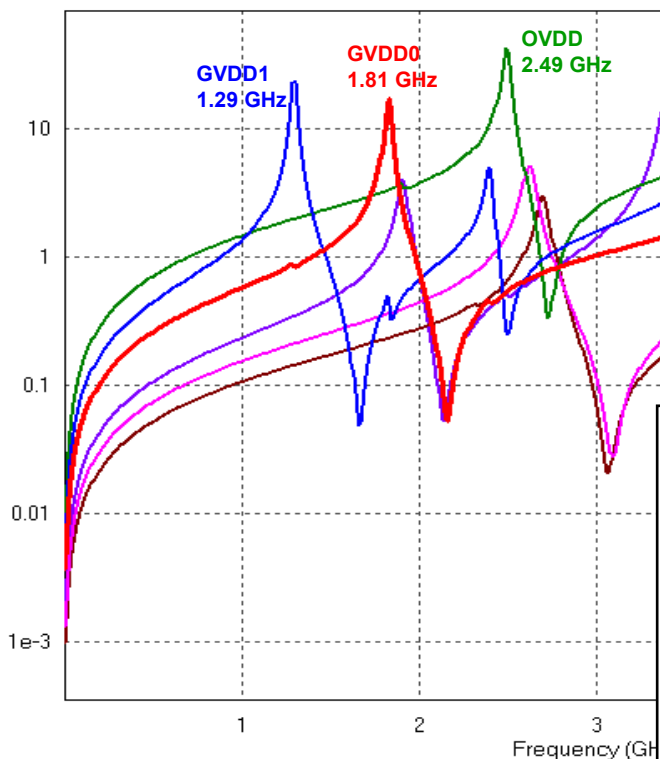
# Single-segment RLCK Model vs. Extraction Frequency

Extraction Frequency  
 {30, 100, 200, 400} MHz



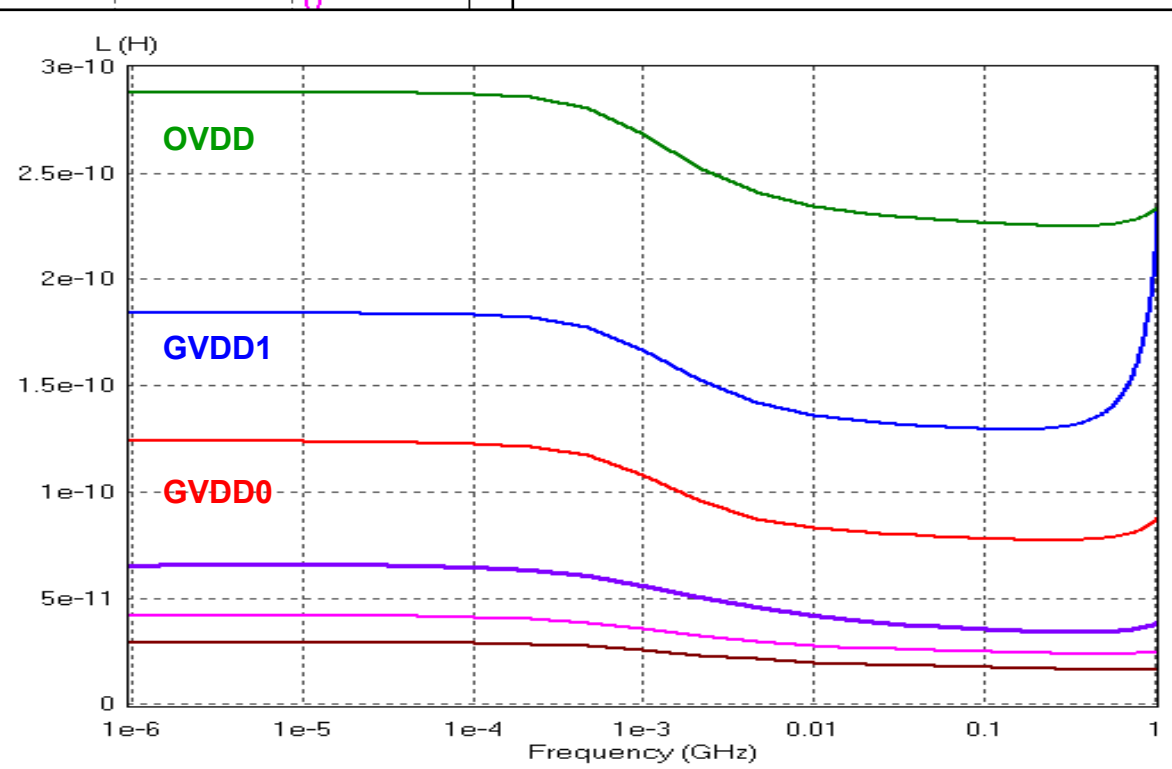
# Broadband Impedance and Extracted Loop Inductance

Z Amplitude (Ohm)



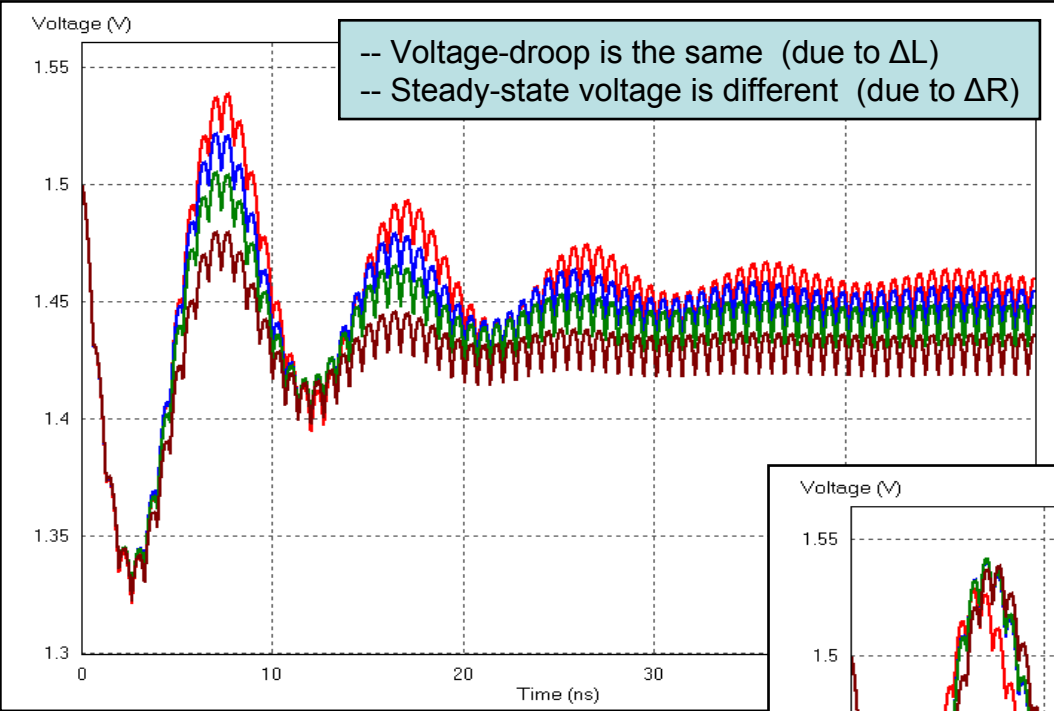
L(freq) behaves as expected – internal inductance decreases as DC bulk current flow transitions to AC skin current.

1-segment RLCK model breaks down as we approach  $\approx 20\%$  of net resonance. Specifically, L value increases rapidly with frequency.

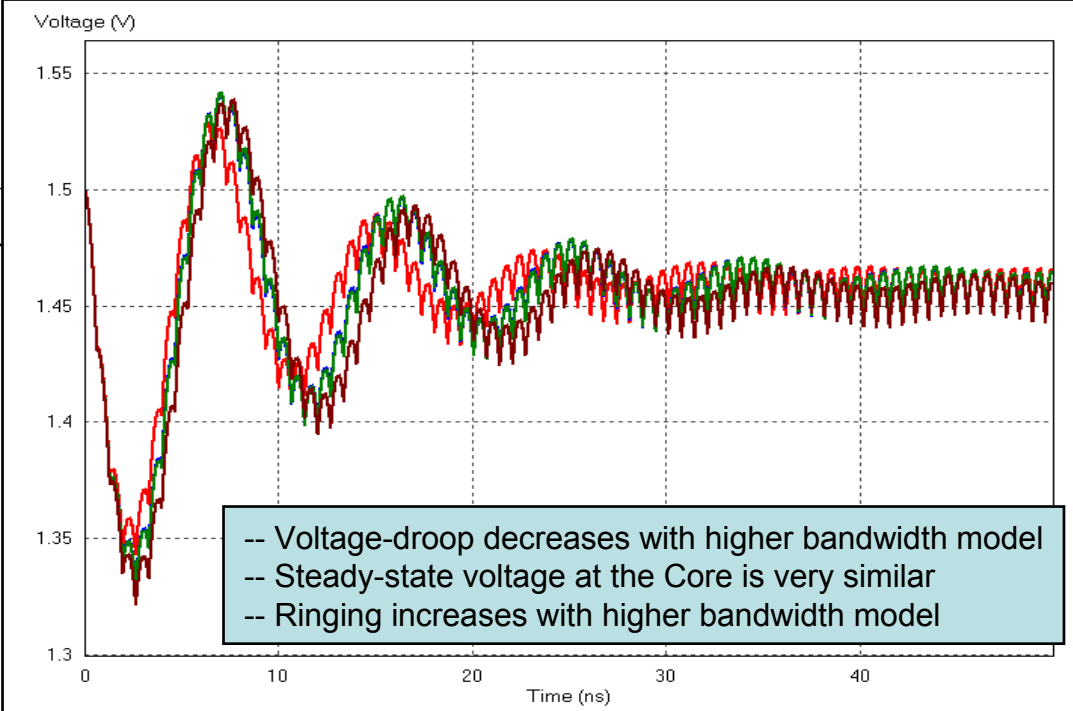


# Core Noise Voltage for Pulsed Core Current

$P_{av} = 25W$ ,  $V = 1.5 V$ ,  $f = 1.5 GHz$ ,  $C_{die} = 80 nF$ ,  $R_g = 4 m\Omega$



**Single-segment model**  
**{30, 100, 200, 400} MHz**

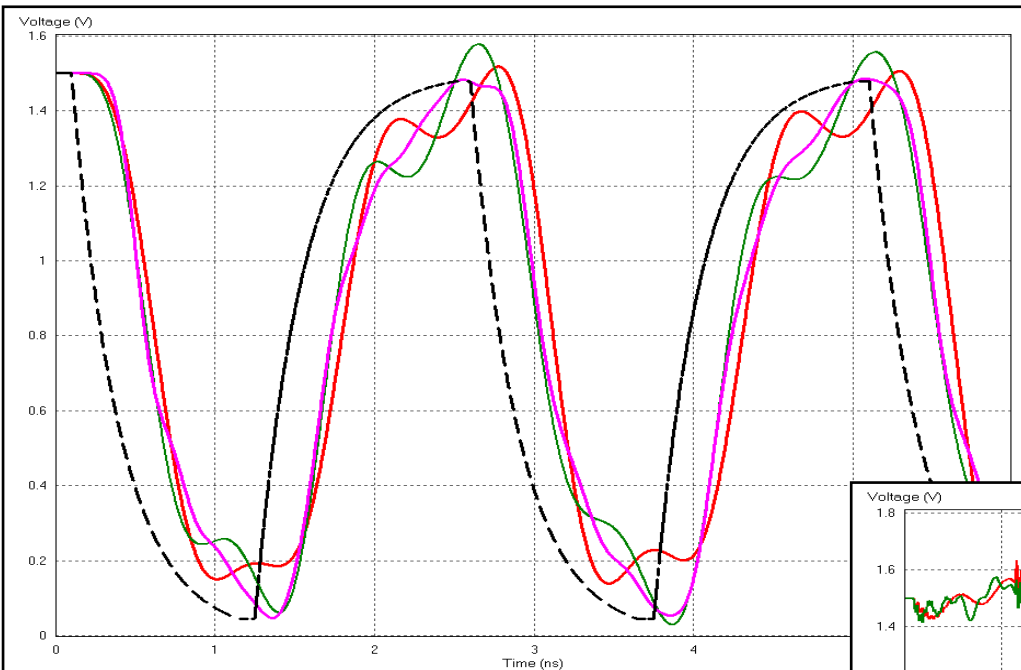


**Model Type:**  
**1-segment, 30 MHz**  
**3-segment, 2 GHz**  
**3-segment, 6 GHz**  
**S-parameters**



# SSN at Load with 14-of-16 DDR Signals Switched

$F_{\text{switch}} = 400 \text{ MHz}$  ,  $T_{\text{rise}} = T_{\text{fall}} = 100 \text{ ps}$  with



## Model Type:

None

1-segment, 30MHz

1-segment broadband 2GHz

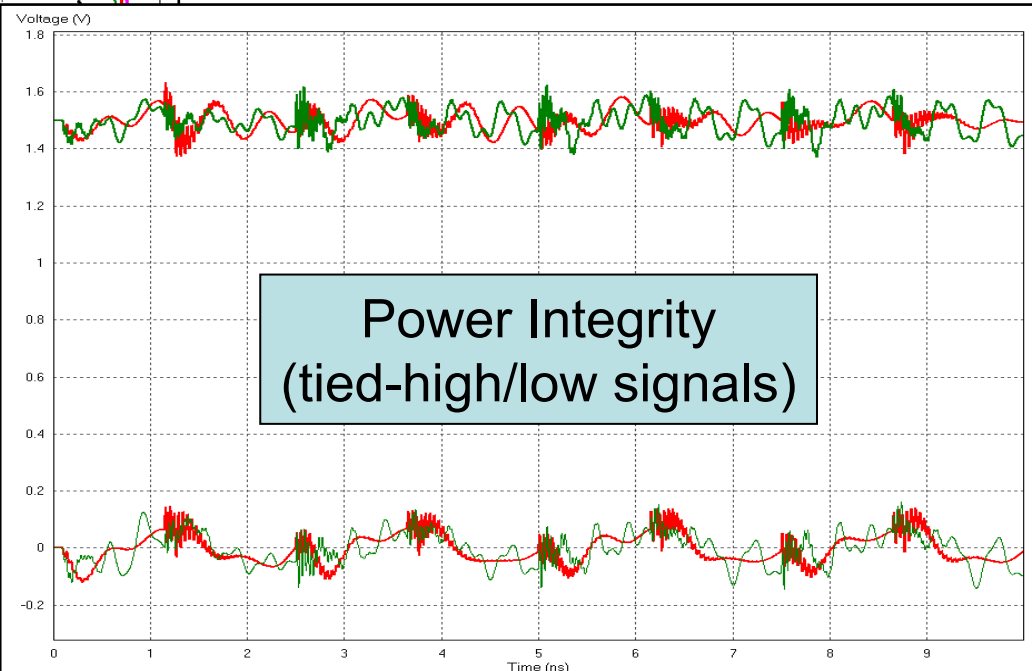
3-segment broadband 2GHz

## Signal Integrity

## Model Type:

1-segment broadband, 2GHz

3-segment broadband, 2GHz



## Power Integrity (tied-high/low signals)

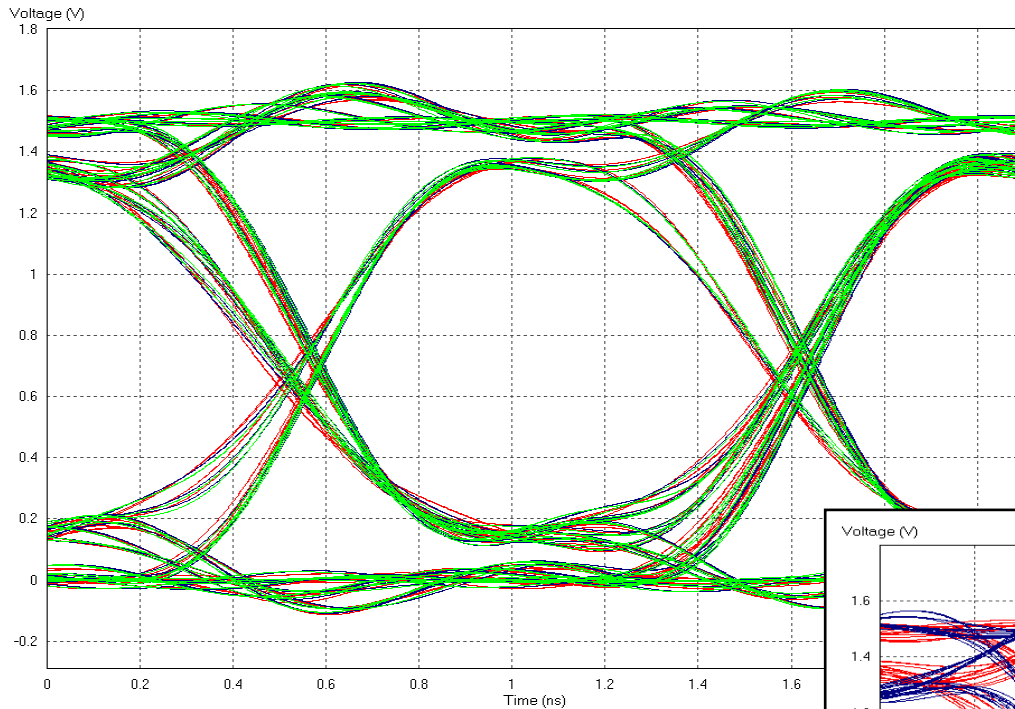
# Eye Diagram at the Load

$$F_{\text{switch}} = 400 \text{ MHz} , T_{\text{rise}} = T_{\text{fall}} = 100 \text{ ps}$$

## Single-segment model

{30, 100, 200} MHz

- Similar eye openings
- A bit more jitter with lower extraction frequency

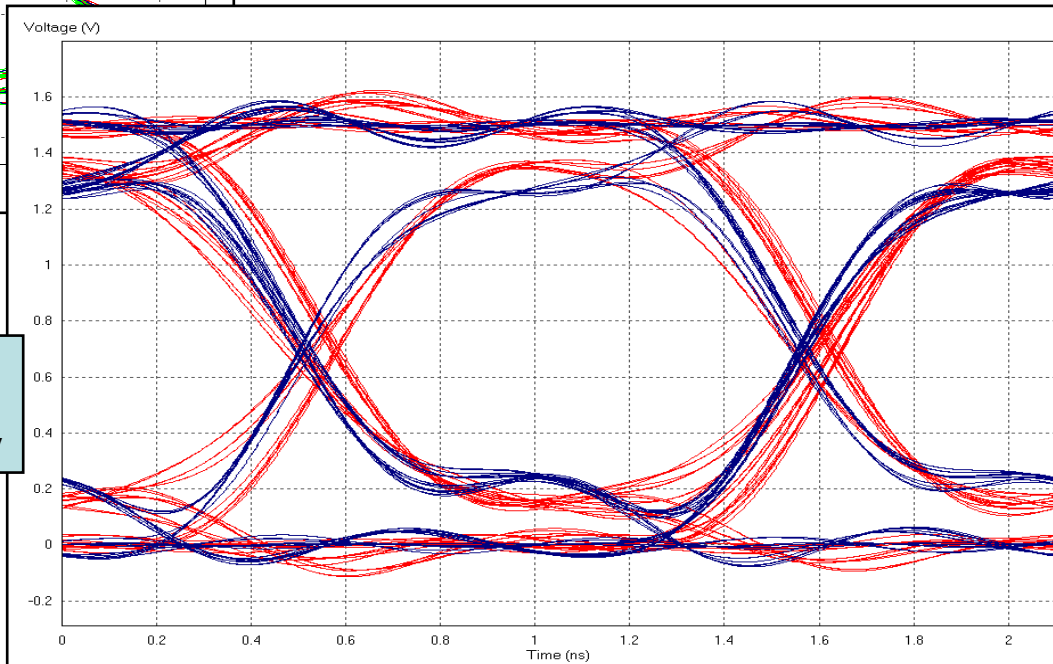


- Very similar eye openings
- Overshoot/Undershoot and ringback are very similar
- Significantly more jitter with single extraction frequency

## Single-segment model

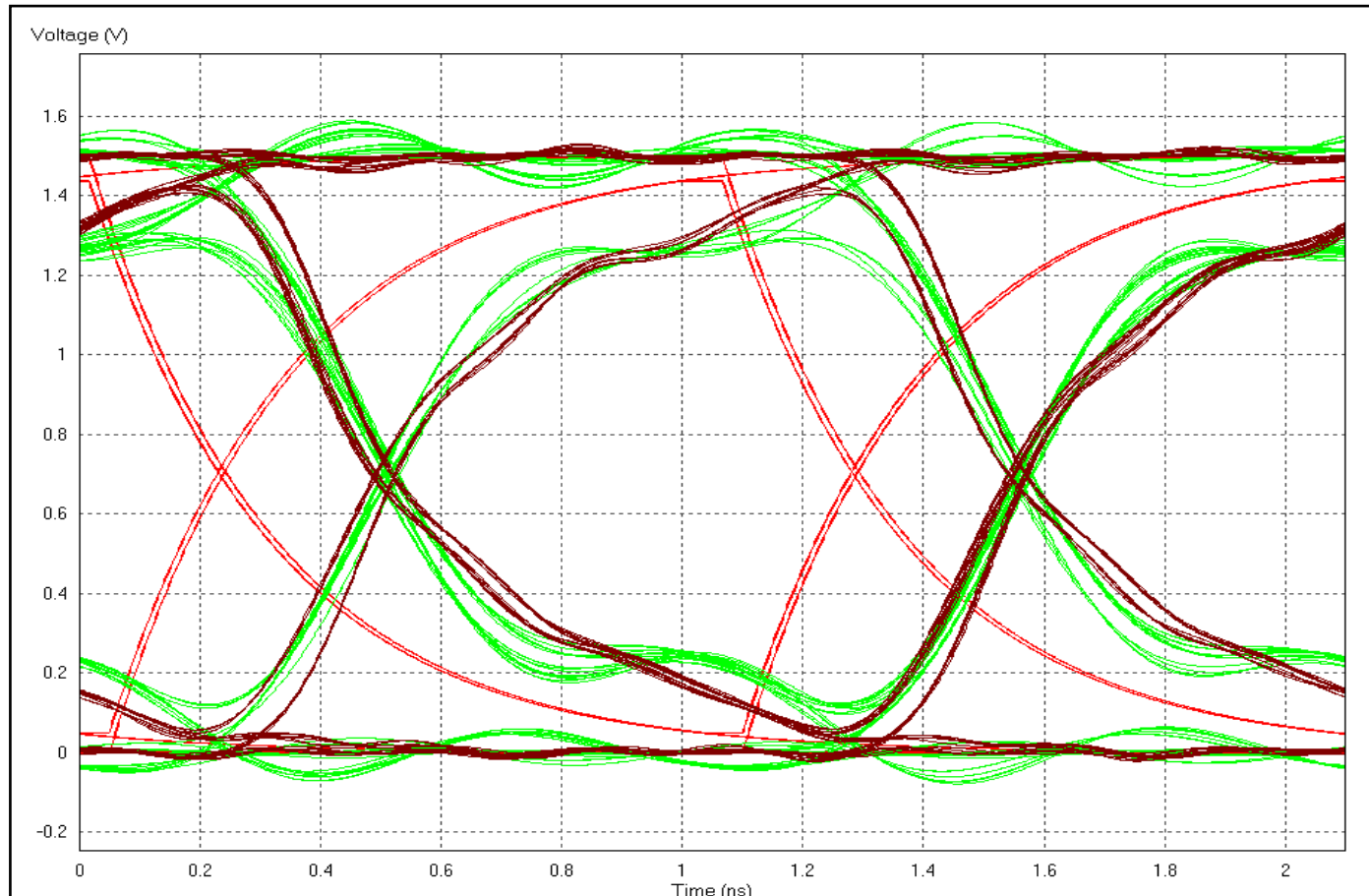
30 MHz

broadband, 2GHz



# Eye Diagram at the Load

$$F_{\text{switch}} = 400 \text{ MHz} , T_{\text{rise}} = T_{\text{fall}} = 100 \text{ ps}$$



## Model Type:

None

1-segment broadband, 2GHz

3-segment broadband, 2GHz

- Package model effects are quite dramatic
- Similar eye openings for each broadband model
- Overshoot/Undershoot and ringback are quite different
- Similar jitter for each broadband model

# Conclusions:

- System noise performance differs for various types of package models and the conditions under which they are extracted
  - Loop inductance, AC resistance, voltage droop, power bounce, eye diagrams and jitter are used as figure of merits for noise performance evaluation
  - **Broadband data based, multi-segment models predict more realistic SI-PI performance with significant differences for DC single-segment models**
- Extraction frequency affects models and SI-PI performance as expected
  - RLC values vary as intuitively expected
  - RLC values affect signal switching as expected and also affect power noise as might not be expected
  - **Multi-segment broadband based RLCK models correspond best with full-wave S-parameter SI-PI performance predictions**
- Lessons learned for system-level modeling and design
  - **select appropriate package model type for signal bandwidths**
  - **extract package models with adequate bandwidth**
  - proper models enable efficiency of iterative simulation-based design improvements of for high performance processor and ASIC packages